

AMENDMENTS TO THE CLAIMS

Please cancel claims 1, 4, 9, 11, 17, 18 and 20, and amend claims 5 and 7, in accordance with the following list of claims:

1-2. (Canceled)

3. (Previously Presented) A semiconductor chip package, comprising:

a first integrated semiconductor chip having a first chip size, having a one side and a reverse side, and having a first electrode for wiring on the one side of the first integrated semiconductor chip;

a second integrated semiconductor chip having a second chip size, having a one side and a reverse side, and having a second electrode for wiring on the one side of the second integrated semiconductor chip, the first integrated semiconductor chip being mounted to the second integrated semiconductor chip with the reverse side of the second integrated semiconductor chip facing the reverse side of the first integrated semiconductor chip;

a nonconductive interposer substrate having opposite first and second surfaces, and having a through-hole extending therethrough from the first surface to the second surface, the through-hole being larger than the second chip size;

an adhesive sheet having opposite first and second surfaces, the adhesive sheet being formed of a sheet-shaped adhesive material provided on the interposer substrate at the first surface of the interposer substrate so as to cover the through-hole, the second surface of the adhesive sheet being exposed through the through-hole from a side of the interposer substrate at the second surface of the interposer substrate,

wherein the reverse side of the second integrated semiconductor chip is fixed to the second surface of the adhesive sheet, and the reverse side of the first integrated semiconductor chip is fixed to the first surface of the adhesive sheet so as to face the reverse side of the second integrated semiconductor chip at a position at which the second integrated semiconductor chip is fixed, whereby the second electrode can be wired to external terminals on the second surface of the interposer substrate.

4. (Canceled)

5. (Currently Amended) A semiconductor chip package according to ~~claim 1~~, comprising:

a first integrated semiconductor chip having a one side and a reverse side, and having a first electrode for wiring on the one side of the first integrated semiconductor chip;

a nonconductive interposer substrate having opposite first and second surfaces, and having a through-hole extending therethrough from the first surface to the second surface;

a second integrated semiconductor chip having a one side and a reverse side, and having a second electrode for wiring on the one side of the second integrated semiconductor chip, the second integrated semiconductor chip being mounted on the first surface of the interposer substrate with the one side of the second integrated semiconductor chip facing the first surface of the interposer substrate, such that the second electrode is exposed through the through-hole, the second electrode to be wired through the through-hole to external terminals on the second surface of the interposer substrate,

the first integrated semiconductor chip being mounted on the reverse side of the second integrated semiconductor chip with the reverse side of the first integrated semiconductor chip facing the reverse side of the second integrated semiconductor chip, and

wherein the interposer substrate has a sunken region, which is sunken into the side of the interposer substrate at the second surface of the interposer substrate, and the through-hole is provided through the sunken region.

6. (Previously Presented) A semiconductor chip package according to claim 3, wherein the interposer substrate has, a sunken region, which is sunken into the side of the interposer substrate at the second surface of the interposer substrate, and the through-hole is provided through the sunken region.

7. (Currently Amended) A semiconductor chip package according to ~~claim 4~~, comprising:

a first integrated semiconductor chip having a first chip size, having a one side and a reverse side, and having a first electrode for wiring on the one side of the first integrated semiconductor chip;

a second integrated semiconductor chip having a second chip size and having a one side and a reverse side, the first integrated semiconductor chip being mounted to the second integrated semiconductor chip with the reverse side of the second integrated semiconductor chip facing the reverse side of the first integrated semiconductor chip; and

an interposer substrate having a through-hole, the through-hole being smaller than the first chip size and larger than the second chip size,

wherein the first integrated semiconductor chip is mounted via an adhesive sheet on the first surface of the interposer substrate at a portion of the reverse side of the first integrated semiconductor chip, such that the through-hole is covered by the first integrated semiconductor chip and the adhesive sheet,

wherein the reverse side of the second integrated semiconductor chip is fixed to the reverse side of the first integrated semiconductor chip, the adhesive sheet on the reverse side of the first integrated semiconductor chip being exposed through the through-hole from a side of the interposer substrate at the second surface of the interposer substrate, and

wherein the interposer substrate has a sunken region, that is sunken into the side of the interposer substrate at the second surface of the interposer substrate, and the through-hole is provided through the sunken region.

8. (Previously Presented) A semiconductor chip package, comprising:

a first integrated semiconductor chip having a first chip size, having a one side and a reverse side, and having a first electrode for wiring on the one side of the first integrated semiconductor chip;

a second integrated semiconductor chip having a second chip size, having a one side and a reverse side, and having a second electrode for wiring on the one side of the second integrated semiconductor chip, the first integrated semiconductor chip being mounted to the second integrated semiconductor chip with the reverse side of the second

integrated semiconductor chip facing the reverse side of the first integrated semiconductor chip;

a nonconductive interposer substrate having opposite first and second surfaces, and having a through-hole extending therethrough from the first surface to the second surface; and

an adhesive sheet formed of sheet-shaped adhesive material at the first surface of the interposer substrate so as to cover the through-hole, the adhesive sheet being larger than the second chip size and having a hole smaller than the second chip size,

wherein the second integrated semiconductor chip is fixed, at the one side of the second integrated semiconductor chip, to the first surface of the interposer substrate via the adhesive sheet, and

wherein the second electrode for wiring is exposed from the side of the interposer substrate at the second surface of the interposer substrate through the adhesive sheet small hole and the through-hole of the interposer substrate.

9. (Canceled)

10. (Previously Presented) A semiconductor chip package according to claim 3, wherein the interposer substrate is formed of one of nonconductive tape and a glass epoxy material.

11. (Canceled)

12. (Previously Presented) A semiconductor chip package according to claim 8, wherein the interposer substrate is formed of one of a nonconductive tape and a glass epoxy material.

13. (Previously Presented) A semiconductor chip package according to claim 3, wherein both surfaces of the adhesive sheet become viscous when heated.

14. (Previously Presented) A semiconductor chip package according to claim 8, wherein both surfaces of the adhesive sheet become viscous when heated.

15. (Previously Presented) A semiconductor chip package according to claim 8, wherein the interposer substrate has external terminals on its second surface to which the second electrode can be wired, and external terminals on its first surface to which the first electrode can be wired.

16. (Previously Presented) A semiconductor chip package according to claim 15, further comprising:

a plurality of solder balls mounted to the second surface of the interposer substrate, the solder balls being electrically connected to respective ones of the external terminals on the first and second surfaces of the interposer substrate.

17-18. (Canceled)

19. (Previously Presented) A semiconductor chip package according to claim 3, wherein the interposer substrate has external terminals on its first surface to which the first electrode can be wired, and the semiconductor chip package further comprises a plurality of solder balls mounted to the second surface of the interposer substrate, the solder balls being electrically connected to respective ones of the external terminals on the first and second surfaces of the interposer substrate.

20. (Canceled)